External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.43898	100.0	1
			Subtotal	0.43898	100	1
Post-plating	Tin solder	Bismuth (Bi)	7440-69-9	0	0.0	0
	Tin solder	Tin (Sn)	7440-31-5	1.61529	99.99	3.67963
	Tin solder	Copper (Cu)	7440-50-8	0	0.0	0
	Tin solder	Lead (Pb)	7439-92-1	0.00016	0.01	0.00037
	Tin solder	Antimony (Sb)	7440-36-0	0	0.0	0
			Subtotal	1.61545	100	3.68
Lead Frame	Copper alloy	Misc. Phosphor compounds (generic)	7723-14-0	0.00788	0.02	0.01794
	Copper alloy	Iron (Fe)	7439-89-6	0.03151	0.08	0.07178
	Copper alloy	Copper (Cu)	7440-50-8	39.26727	99.7	89.45084
	Pure metal layer	Silver (Ag)	7440-22-4	0.07877	0.2	0.17944
			Subtotal	39.38543	100	89.72
Adhesive	Polymer	Paraffin wax	8002-74-2	0.21949	20.0	0.5
	Polymer	Epoxy resin system		0.0878	8.0	0.2
	Filler	Silver (Ag)	7440-22-4	0.79017	72.0	1.8
			Subtotal	1.09746	100	2.5
Mould Compound	Polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	1.43624	2.5	3.27175
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	4.30871	7.5	9.81525
	Filler	Silica -amorphous-	7631-86-9	21.25632	37.0	48.4219
	Pigment	Carbon black	1333-86-4	0.28725	0.5	0.65435
	Polymer	Epoxy resin system		8.61743	15.0	19.6305
	Filler	Silicon Dioxide (SiO2)	14808-60-7	21.25632	37.0	48.4219
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.28725	0.5	0.65435
			Subtotal	57.44952	100	130.87
Wire	Pure metal	Copper (Cu)	7440-50-8	0.01317	100.0	0.03
			Subtotal	0.01317	100	0.03
			Total	100.00001	100	227.8

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